Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1		("20060163559").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/20 18:40
L2	4	(("6146913") or ("6344380")).PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/20 18:54
L3.	8588	organic near semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 18:55
L4	225627	(field near effect near transistor) or \$2FET	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 18:56
L5	1581	L3 and L4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 18:57
L6	176482	surface near rough\$6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/11/20 18:56
L7	89	L5 and L6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 18:56

L8	42	L7 and @ad<"20030331"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT;	OR	ON	2006/11/20 18:58
L9	176	(polyimide and (glass near epoxy) and ((\$4ethylene adj terephthalate) or PET)) with substrate	IBM_TDB US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/11/20 19:36
L10	6258	(polyimide and ((glass near epoxy) or ((\$4ethylene adj terephthalate) or PET))) with substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 19:36
L11	6	13 and 19	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 19:35
L12	9404	(polyimide and ((glass near epoxy) or ((\$4ethylene adj terephthalate) or PET))) same substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 19:36
L13 -	413	L3 and L12	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 19:37
L14	276	(polyimide and (glass near epoxy) and ((\$4ethylene adj terephthalate) or PET)) same substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2006/11/20 19:36

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L15	12	L3 and L14	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 19:36
L16		L13 and @ad<"20030331"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 19:46
L17	8	L16 and (electrode with rough\$6)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 19:43
L18	102	L16 and flexible	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 20:27
L19	63127	cmp	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 20:27
L20	38839	ITO with electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 20:27
L21	42311	ITO with (electrode or anode or cathode)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 20:39

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L22		L20 with L21	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 20:27
L23	. 11	L19 with L21	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/11/20 20:27
L24	42452	planarization	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 20:29
L25	72389	planariz\$6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 20:29
L26	3684	L21 and L25	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/11/20 20:29
L27	975	L21 same L25	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 20:29
L28	507	L21 with L25	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 20:30

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L29	281	L28 and @ad<"20030331"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 20:30
L30	57	(L21 with L25) same ((cmp or (chemical near mechanical near polish\$4)) or etch\$4 or (polish\$4 near tape))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 20:49
L31	195676	gate near (electrode or anode or cathode)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/11/20 20:39
L32	1302	(L31 with L25) same ((cmp or (chemical near mechanical near polish\$4)) or etch\$4 or (polish\$4 near tape))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 20:45
L33	804	L32 and @ad<"20030331"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/11/20 20:44
L34	1	L33 and (257/40.ccls. or 438/99. clas.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 20:42
L35	8588	organic near semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 20:43

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L36	0	L33 and L35	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR .	ON .	2006/11/20 20:44
L37	36	L30 and @ad<"20030331"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 21:10
L38	. 23	CMP with average with rough\$4 with (angstrom or nm or nanometer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/20 21:13
L39	180	CMP with rough\$4 with (angstrom or nm or nanometer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/11/20 21:13

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